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The document following this cover page is marked as "Cypress" document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.



CYFP1002XXXX

CYFP1-8080 Datasheet

Features

Fingerprint Sensor

- BGA package consisting of die mounted on a polymer substrate sensor
- □ 8.0 mm × 8.0 mm active imaging area fingerprint sensor
- □ 340 DPI 107 × 107 pixel array at 8-bits per pixel resolution
- Great image quality with polymer, plastic, and ceramic coatings < 100µ in overall thickness
- □ 32-bit Arm[®] Cortex[®]-M0 CPU
- D Noise-suppression technologies for the battery chargers, displays, and radios in the device
- Self-calibration and self-testing
- □ Factory tuned with on-chip baseline storage, no field tuning required
- Secure firmware upgrades via bootloader

System Performance

- Live Finger Complete Acquisition Time (Get Image): ~160ms)
- □ 14 Finger Identify Match Time: ~500ms (average)
- <1.5% FRR at FAR >1:100K using CY-supplied matching SW
- 360 degree finger placement

Embedded Environment

- Embedded Framework (CYFPEF) provided for porting into host processor
- □ Recommended MCU Features: Cortex M4, 256KB of flash, and 96KB of RAM
- Ability to import and export templates securely
- □ Configurable security levels (1:10K to 1:1000K)
- Simple secure external communication protocol over MCU UART Interface

Sensor Communication Interface

- SPI slave bit rates up to 7.8 Mbps
- Strong 256-bit AES encryption secures the system interface from sensor to the host processor

Power (configuration-dependent)

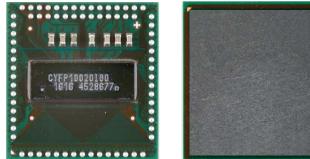
- Operation of single 3.3-V supply
- 1.71 V to 1.95 V direct digital supply or 2.0 V to 5.5 V via LDO
- □ 2.65 V to 5.5 V analog supply
- □ <80-mW active power (average power while sensing)
- □ 8-µW typical deep-sleep power
- □ 400-µW Finger detection power @ 10 detects per second
- Operating Temperature Range □ -40 °C to +85 °C
- Package Options

BGA package, 8.87 × 9.26 mm rectangular sensor

Optional Features

- False finger rejection limiting host processor interruptions
- Fake finger rejection (anti-spoofing)
- Programmable finger detection timing (Wake-on-Finger)
- Navigation

Sensor Shown With Coating



Back of the Sensor



Front of the Sensor

SUMMARY

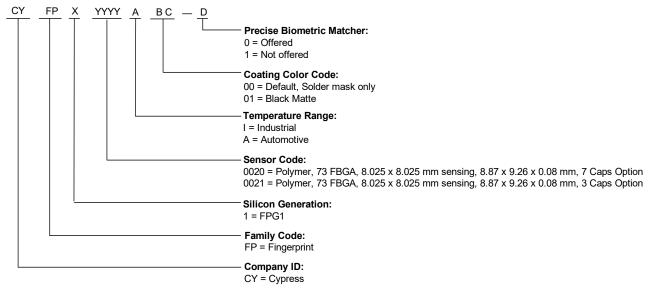


Ordering Information

Table 1. CYFP1 Device Key Features and Ordering Information

| Silicon Type | Package Type | Package Size | Operating Temperature |
|----------------|--------------|---|-----------------------|
| CYFP10020I00 | | 8.87 × 9.26 × 0.80 mm | Industrial |
| CYFP10020I01 | | | |
| CYFP10020I01-1 | | | |
| CYFP10021I00 | 73-Ball BGA | $12.20 \times 12.20 \times 0.80 \text{ mm}$ | muusinai |
| CYFP10021I01 | | 8.87 × 9.26 × 0.80 mm | |
| CYFP10021I01-1 | | | |

Part Ordering Code Definitions



All devices in the CYFP1 family comply to RoHS-6 specifications, demonstrating the commitment by Cypress to Pb-free products. Lead (Pb) is an alloying element in solders that has resulted in environmental concerns due to potential toxicity. Cypress uses the nickel-palladium-gold (NiPdAu) technology for a majority of the lead frame-based packages.

A high-level review of the Cypress Pb-free position is available on our website. Specific package information is also available. Package Material Declaration Datasheets (PMDDs) identify all substances contained within Cypress packages. PMDDs also confirm the absence of many banned substances. The information in the PMDDs will help Cypress customers plan for recycling or other "end of life" requirements.



Document History Page

Document Title: CYFP1002XXXX, CYFP1-8080 Datasheet

| Document Number: 002-11237 | | | | | |
|----------------------------|---------|--------------------|--------------------|---|--|
| Revision | ECN | Orig. of Change | Submission Date | Description of Change | |
| ** | 5142470 | HFO | 02/18/2016 | New datasheet. | |
| *A | 5363615 | HFO | 08/19/2016 | Updated Features and added board image. | |
| *В | 6283450 | HFO | 09/19/2018 | Updated template. Updated Features and Ordering Information. | |



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